ABBOCIATION CONNECTING ELECTRONICS INDUSTRIES* international and	position De . IPC, Bannockt Pan-American co	claration ourn, Illinois. A opyright conve	All rights reserved u ntions.	nder both	This docume level parts, th	ent is a declaration er	on of the substand acompasses all lo	es within the mar wer level material	nufacturer liste ls for which the	d item. Note: if e manufacturer	the item is an as has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				Materials and	als and Mfg Information			
upplier Information													
ompany name*	Company unique ID			l	Unique ID Authority				Response Date*				
onsemi										2025-06-04			
Contact Name Title - Contact			t P		Phone - Contact*			Emai	Email - Contact*				
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			Phone - Representative*			Emai	Email - Representative*			
roduct-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number			Number Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	FSFR17	FSFR1700XSL High Pwr FPS f		HB	IB			СРА		1049.548	mg	Each	
Ianufacturing Proccess Inforn	ation					•	-	-				·	
Terminal Plating / Grid Array	Terminal Plating / Grid Array Material Terminal Base A		Alloy J	J-STD-020 MSL Rating		Peak Process Body Temperature Max Time at		at Peak Tempe	ak Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30	sec	conds 3				
omments													
or more information regarding mater	al composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	9.87	mg	Supplier	Silicon (Si)	7440-21-3		9.87	mg	
Die Attach	2.18	mg	Supplier	Silver (Ag)	7440-22-4		0.0327	mg	
			А	Lead (Pb)	7439-92-1	7a	2.0383	mg	
			Supplier	Tin (Sn)	7440-31-5		0.109	mg	
Lead Frame	339.343	mg	Supplier	Zinc (Zn)	7440-66-6		0.407	mg	
			Supplier	Iron (Fe)	7439-89-6		7.805	mg	
			Supplier	Copper (Cu)	7440-50-8		331.0291	mg	
			Supplier	Phosphorus (P)	7723-14-0		0.1019	mg	
Mold Compound-Black	693.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		34.65	mg	
			Supplier	Carbon Black (C)	1333-86-4		6.93	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		616.77	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		34.6499	mg	
Plating	4.92	mg	Supplier	Tin (Sn)	7440-31-5		4.92	mg	
Wire Bond - Cu	0.235	mg	Supplier	Copper (Cu)	7440-50-8		0.235	mg	

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3